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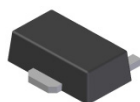


## Features

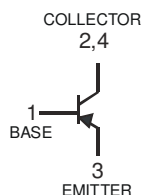
- Epitaxial Planar Die Construction
- Complementary NPN Type Available (DXT5551)
- Ideally Suited for Automated Assembly Processes
- Ideal for Medium Power Switching or Amplification Applications
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**

## Mechanical Data

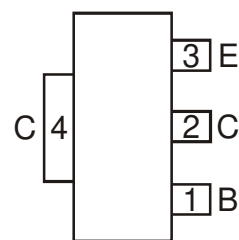
- Case: SOT89-3L
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin annealed over Copper Leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.055 grams (approximate)



Top View



Device Schematic



Pin Out Configuration

## Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-160	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-150	V
Emitter-Base Voltage	V <sub>EBO</sub>	-5.0	V
Collector Current	I <sub>C</sub>	-600	mA

## Thermal Characteristics

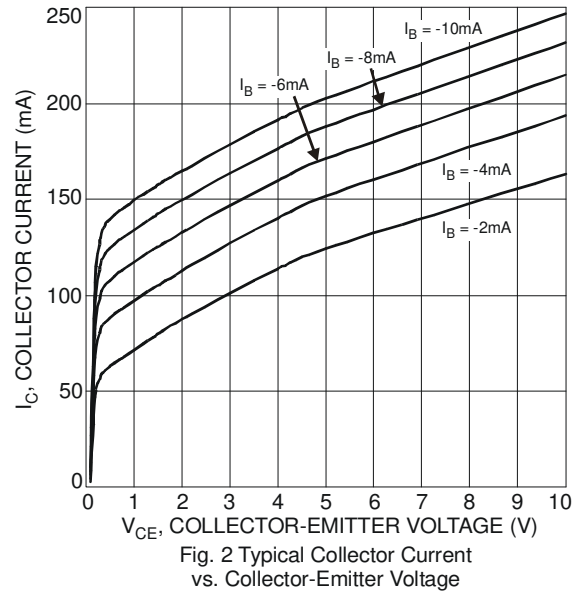
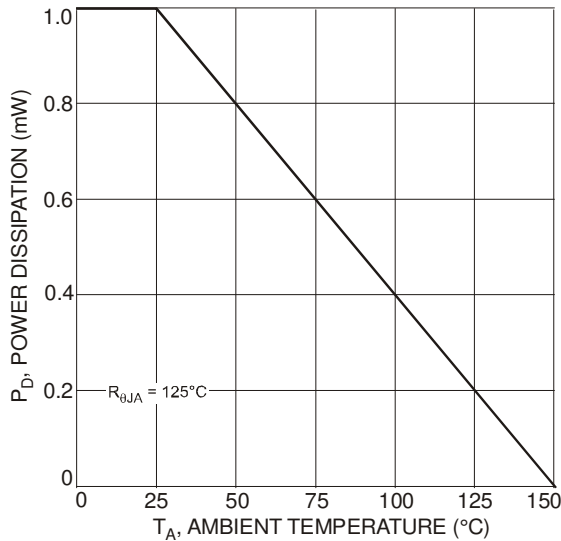
Characteristic	Symbol	Value	Unit
Power Dissipation @T <sub>A</sub> = 25°C (Note 3)	P <sub>D</sub>	1	W
Thermal Resistance, Junction to Ambient @T <sub>A</sub> = 25°C (Note 3)	R <sub>θJA</sub>	125	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

- Notes:
1. No purposefully added lead.
  2. Diodes Inc.'s "Green" policy can be found on our website at [http://www.diodes.com/products/lead\\_free/index.php](http://www.diodes.com/products/lead_free/index.php).
  3. Device mounted on FR-4 PCB, pad layout as shown on page 4 or in Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.

**Electrical Characteristics** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 4)</b>					
Collector-Base Breakdown Voltage	$V_{(BR)CBO}$	-160	—	V	$I_C = -100\mu\text{A}$ , $I_E = 0$
Collector-Emitter Breakdown Voltage	$V_{(BR)CEO}$	-150	—	V	$I_C = -1.0\text{mA}$ , $I_B = 0$
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	-5.0	—	V	$I_E = -10\mu\text{A}$ , $I_C = 0$
Collector Cutoff Current	$I_{CBO}$	—	-50	nA $\mu\text{A}$	$V_{CB} = -120\text{V}$ , $I_E = 0$ $V_{CB} = -120\text{V}$ , $I_E = 0$ , $T_A = 100^\circ\text{C}$
Emitter Cutoff Current	$I_{EBO}$	—	-50	nA	$V_{EB} = -3.0\text{V}$ , $I_C = 0$
<b>ON CHARACTERISTICS (Note 4)</b>					
DC Current Gain	$h_{FE}$	50 60 50	— 240 —	—	$V_{CE} = -5.0\text{V}$ , $I_C = -1.0\text{mA}$ $V_{CE} = -5.0\text{V}$ , $I_C = -10\text{mA}$ $V_{CE} = -5.0\text{V}$ , $I_C = -50\text{mA}$
Collector-Emitter Saturation Voltage	$V_{CE(SAT)}$	—	-0.2 -0.5	V	$I_C = -10\text{mA}$ , $I_B = -1.0\text{mA}$ $I_C = -50\text{mA}$ , $I_B = -5.0\text{mA}$
Base-Emitter Saturation Voltage	$V_{BE(SAT)}$	—	-1.0	V	$I_C = -10\text{mA}$ , $I_B = -1.0\text{mA}$ $I_C = -50\text{mA}$ , $I_B = -5.0\text{mA}$
<b>SMALL SIGNAL CHARACTERISTICS</b>					
Output Capacitance	$C_{obo}$	—	6.0	pF	$V_{CB} = -10\text{V}$ , $f = 1.0\text{MHz}$ , $I_E = 0$
Small Signal Current Gain	$h_{fe}$	40	200	—	$V_{CE} = -10\text{V}$ , $I_C = -1.0\text{mA}$ , $f = 1.0\text{kHz}$
Current Gain-Bandwidth Product	$f_T$	100	300	MHz	$V_{CE} = -10\text{V}$ , $I_C = -10\text{mA}$ , $f = 100\text{MHz}$
Noise Figure	NF	—	8.0	dB	$V_{CE} = -5.0\text{V}$ , $I_C = -200\mu\text{A}$ , $R_S = 10\Omega$ , $f = 1.0\text{kHz}$

Notes: 4. Measured under pulsed conditions. Pulse width = 300 $\mu\text{s}$ . Duty cycle  $\leq 2\%$ .





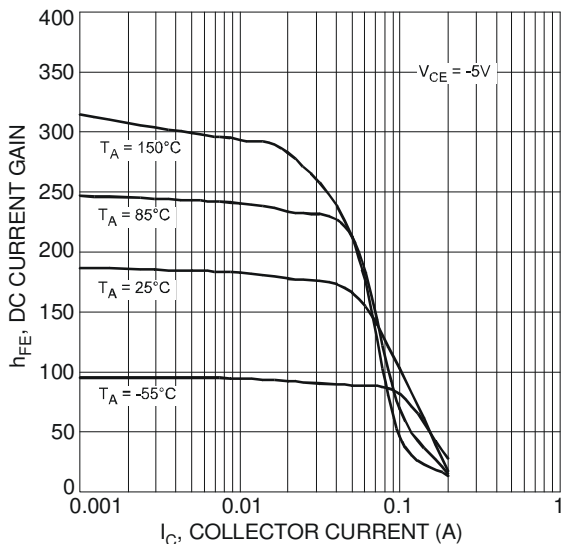


Fig. 3 Typical DC Current Gain vs. Collector Current

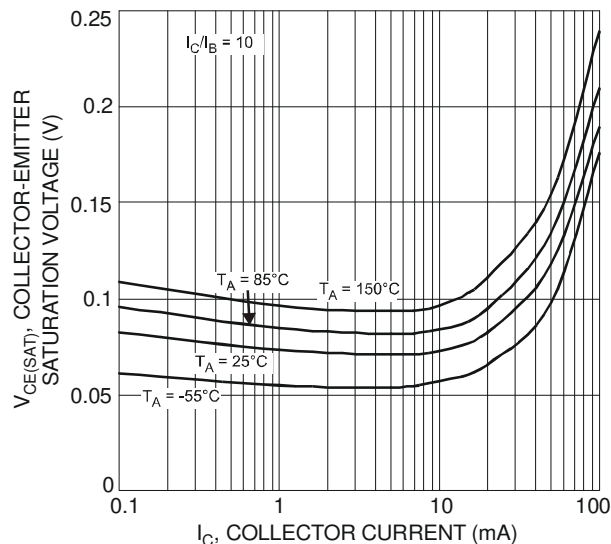


Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

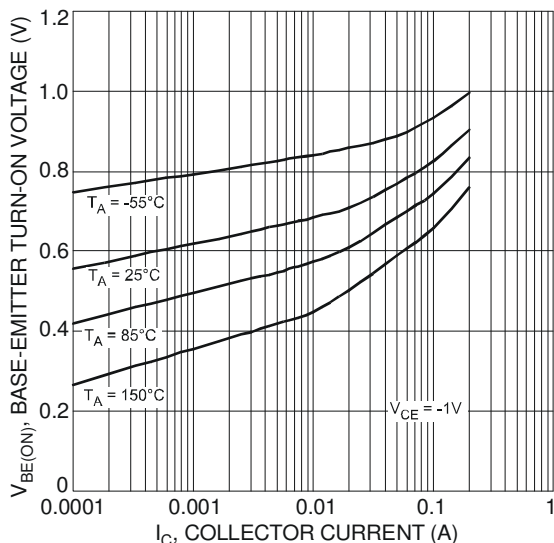


Fig. 5 Typical Base-Emitter Turn-On Voltage vs. Collector Current

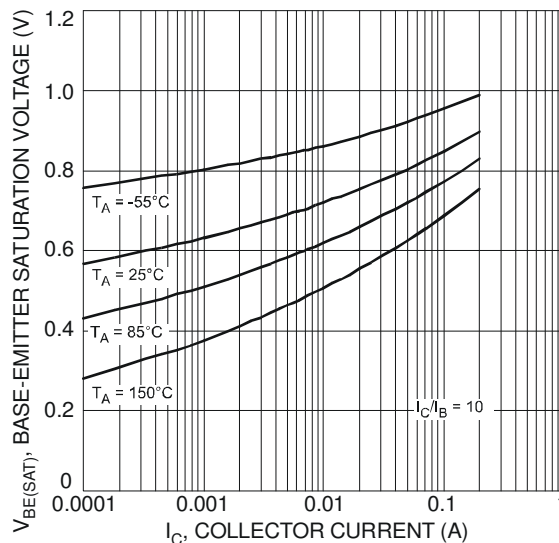


Fig. 6 Typical Base-Emitter Saturation Voltage vs. Collector Current

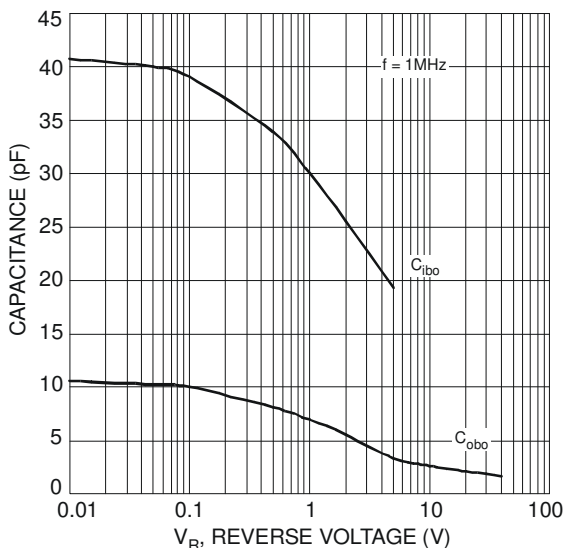


Fig. 7 Typical Capacitance Characteristics

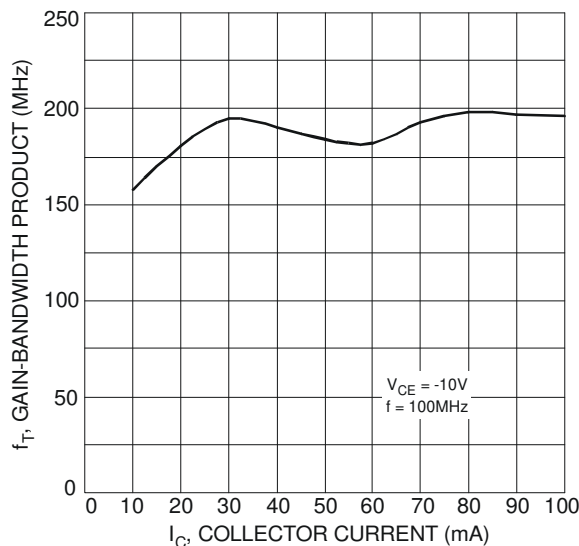


Fig. 8 Typical Gain-Bandwidth Product vs. Collector Current

## Ordering Information (Note 5)

Part Number	Case	Packaging
DXT5401-13	SOT89-3L	2500/Tape & Reel

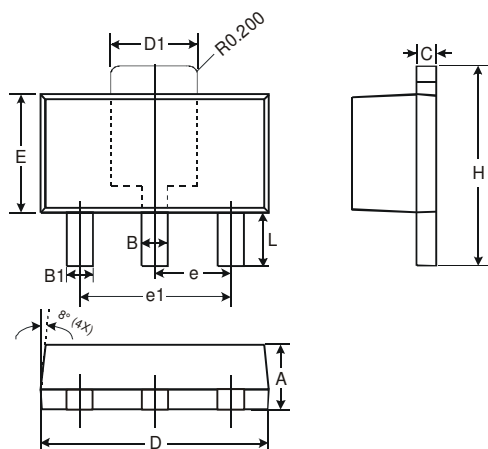
Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

## Marking Information



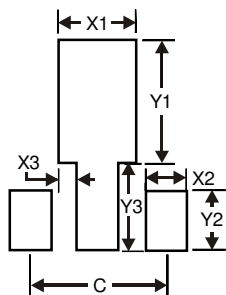
K4M = Product type marking code  
 DII = Manufacturer's code marking  
 YWW = Date code marking  
 Y = Last digit of year (ex: 7 = 2007)  
 WW = Week code (01 – 53)

## Package Outline Dimensions



SOT89-3L		
Dim	Min	Max
A	1.40	1.60
B	0.44	0.62
B1	0.35	0.54
C	0.35	0.43
D	4.40	4.60
D1	1.52	1.83
E	2.29	2.60
e	1.50 Typ	
e1	3.00 Typ	
H	3.94	4.25
L	0.89	1.20
All Dimensions in mm		

## Suggested Pad Layout



Dimensions	Value (in mm)
X1	1.7
X2	0.9
X3	0.4
Y1	2.7
Y2	1.3
Y3	1.9
C	3.0

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